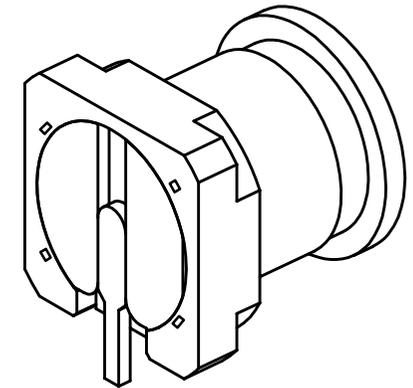
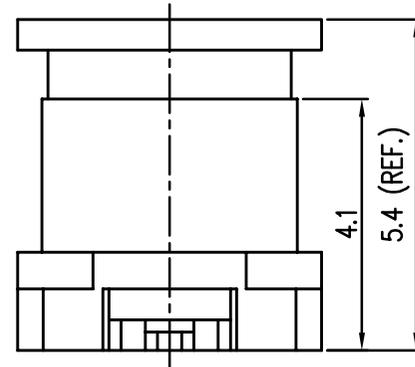
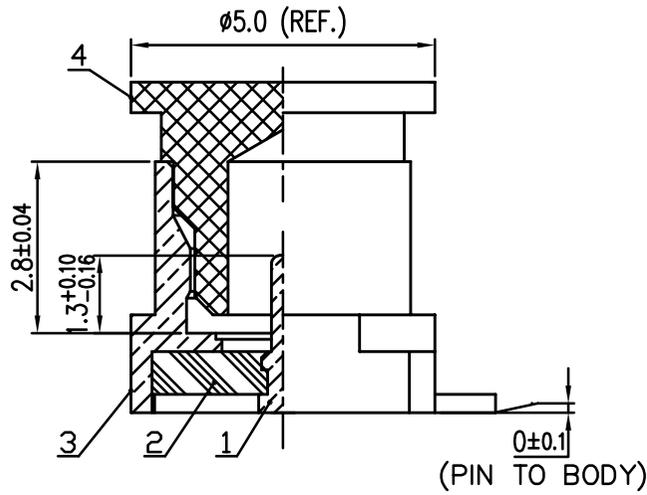
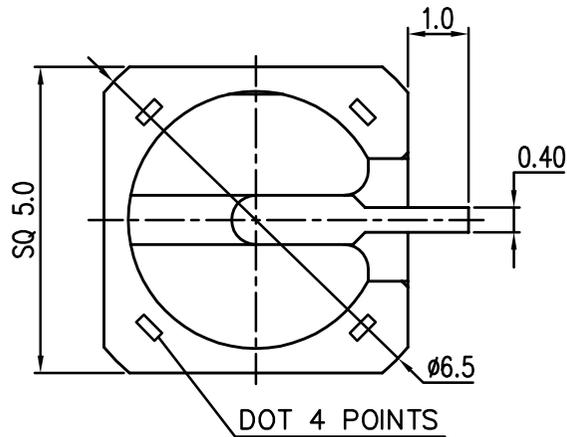


AUTOCAD GENERATED DRAWING. DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.
A	BC-13-0071645	Camvard



3D VIEW



4	COVER	PTFE OR HTN	UL 94V-0	1
3	BODY	COPPER ALLOY	GOLD OVER NICKEL	1
2	INSUATOR	LCP	UL 94V-0	1
1	CONTACT PIN	COPPER ALLOY	GOLD OVER NICKEL	1
ITEM	PART NAME	MATERIAL	FINISH	QTY

COMPONENT PARTS LIST

X.± 0.30	X.*±	UNITS	MM	NAME(INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.20	.X*±	MAT'L		CUSTOMER DRAWING	
.XX± 0.10	.XX*±	SEE NOTES		PART NO.(INTENDED USE)	CLASS: <input checked="" type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input type="checkbox"/> GENERAL
.XXX±	.XXX*±	FINISH		KFP1206-Y027-7F	TITLE: SMP SMT LIMITED DETENT TYPE
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD: Camvard 9/25'2013	DWG NO.: 389-0000-669
				Q'TY	CHKD: Z.H Xu 9/24'2013 DR: River.Chang 9/23'2013
					SCALE SHEET REV. 8:1 1/2 A

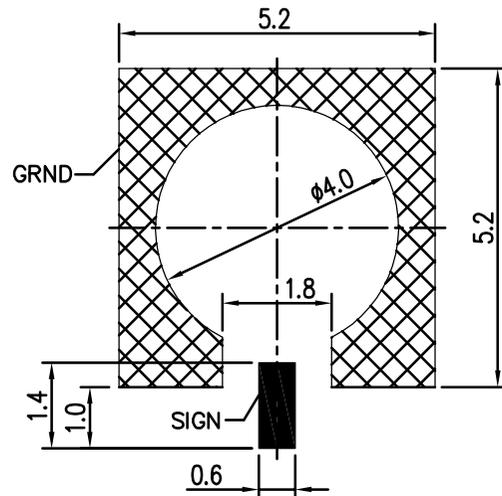
NOTES:

1. INTERFACE STANDARD: MIL-STD-348A(SMP).
2. MATERIAL & FINISH:
 - 2.1 BODY: COPPER ALLOY, GOLD OVER NICKEL PLATED OR SPECIAL REQUIREMENT.
 - 2.2 INSULATOR: LCP, WHITE, UL 94V-0.
 - 2.3 CONTACT PIN: COPPER ALLOY, GOLD OVER NICKEL PLATED OR SPECIAL REQUIREMENT.
 - 2.4 COVER: PTFE(ONLY FOR SAMPLE), HTN(FOR MASS PRODUCTION), UL 94V-0.
3. ELECTRICAL:
 - 3.1 IMPEDANCE: 50Ω(NOMINAL).
 - 3.2 FREQUENCY RANGE: DC TO 6GHz.
 - 3.3 VSWR: 1.2 MAX.(DC TO 4GHz)(FOR INTERFACE ONLY, REACHABLE VALUES IN APPLICATION DEPENDS DECISIVE ON LAYOUT OF PCB).
 - 3.4 CENTER CONTACT RESISTANCE: 6.0mΩ MAX..
OUTER CONTACT RESISTANCE: 2.0mΩ MAX..
 - 3.5 INSULATION RESISTANCE: 5000MΩ MIN..
 - 3.6 DIELECTRIC WITHSTANDING VOLTAGE 500V(AC).
4. MECHANICAL & ENVIRONMENTAL:
 - 4.1 MECHANICAL DURABILITY: 500CYCLES MIN..
 - 4.2 CENTER CONTACT CAPTIVATION FORCE: 7N MIN..
 - 4.3 ENGAGEMENT FORCE: 45N MAX..
 - 4.4 DISENGAGEMENT FORCE: 9N MIN..
 - 4.5 TEMPERATURE RANGE: -65°C TO +155°C.
5. RECOMMENDED PROCESS CONDITION: IR-REFLOW, 260°C, 10s.
6. HARMFUL MATERIAL CONTROL FOLLOW ROHS COMPLIANCE.

REMARK:

PRODUCT NO. : K F P 1 2 0 6 - Y 0 2 7 - 7 F

SERIES PREFIX:	KF=RF COAXIAL CONN.	LEAD FREE CODE	F= LEAD FREE
PROTOCOL TYPE	P=SMP TYPE	PACKAGE	7= TAPE & REEL
CONFIGURATION	1=PIN(PLUG)	FLOWING CODE	
ATTACHMENT	2=PCB SMT	BODY PLATED	Y=GOLD 5μ"/NICKEL 80μ"
IMPEDANCE	0=50Ω	CONTACT PLATED	6=GOLD 10μ"/NICKEL 80μ"



RECOMMENDED PCB PADS
LAYOUT DIM'S, TOL: ±0.05 ALL

X.±	X'.±	UNITS	MM	NAME(INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X±	.X'±	MAT'L		CUSTOMER DRAWING	
.XX±	.XX'±	SEE NOTES		PART NO.(INTENDED USE)	CLASS: <input checked="" type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input type="checkbox"/> GENERAL
.XXX±	.XXX'±	FINISH		KFP1206-Y027-7F	TITLE: SMP SMT LIMITED DETENT TYPE
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